

MECHANICAL CASE OUTLINE

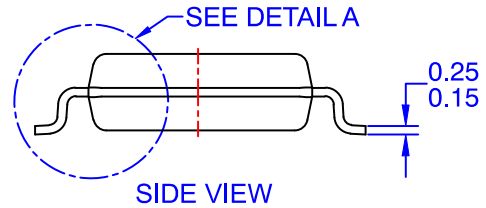
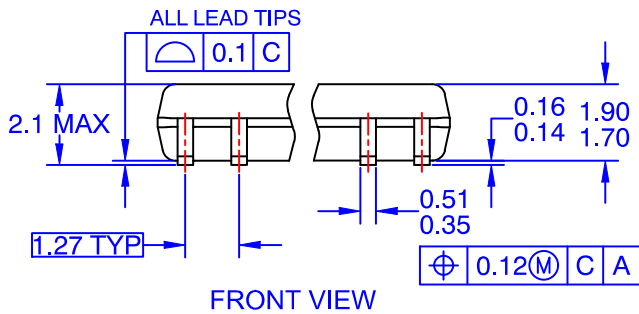
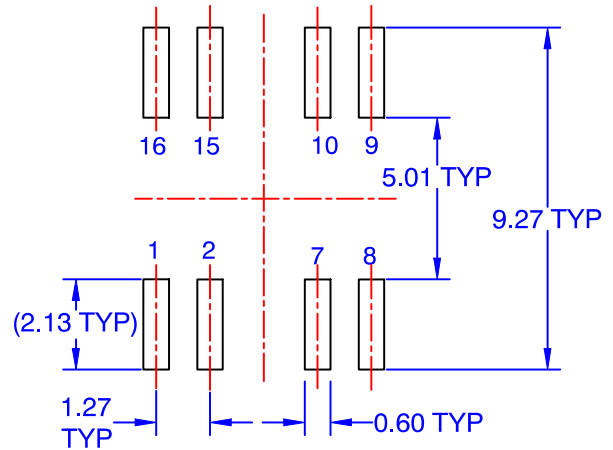
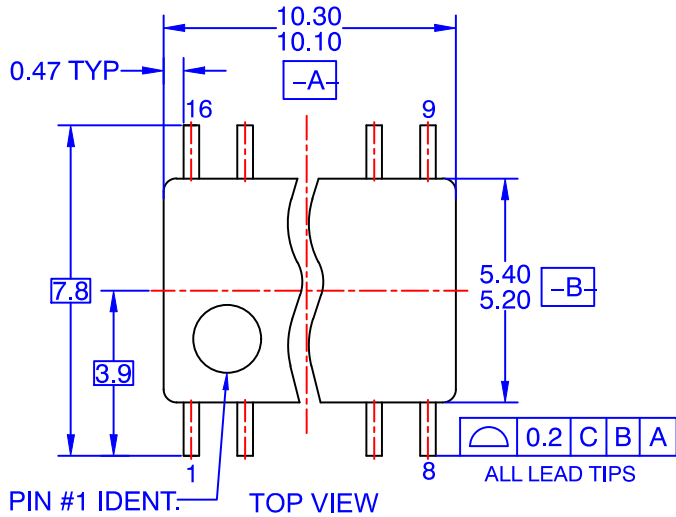
PACKAGE DIMENSIONS

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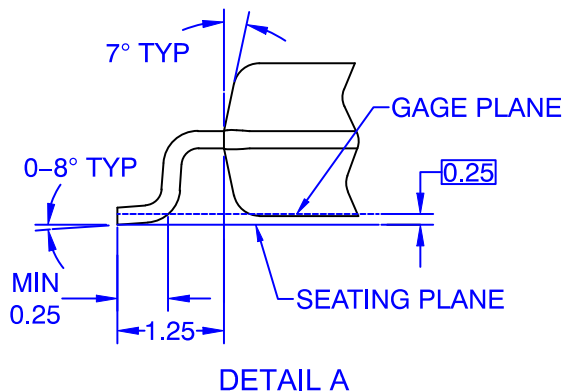
SOP16
CASE 565BF
ISSUE O

DATE 31 DEC 2016



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